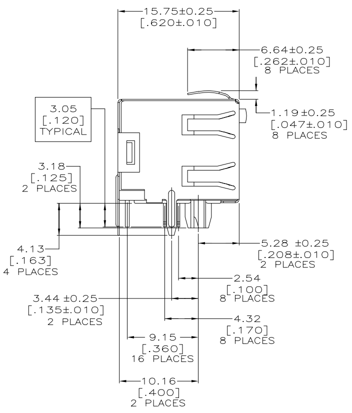
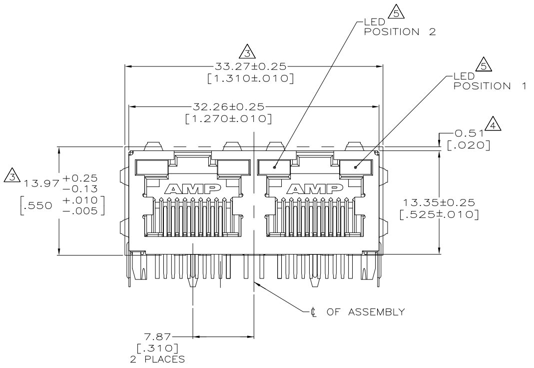
LOC	DIST
AA	22

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	A	REV PER EC 0S11-0201-04	16JUN2005	LV	SF





1 MATERIAL:

HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V–0.

TERMINALS – 0.36[.014] THICK PHOSPHOR BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm[.000050] MINIMUM THICK NICKEL.

SHIELD – 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.000050] MINIMUM SATIN NICKEL WITH 2.03μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm[.0003500] THICK Sn/Cu OVER 2.03 μm[.000080] THICK Ag OVER 1.02μm[.000040] THICK Cu OVER 3.56 μm[.000140] THICK Ni OVER 1.02μm[.000040] Cu UNDERPLATE

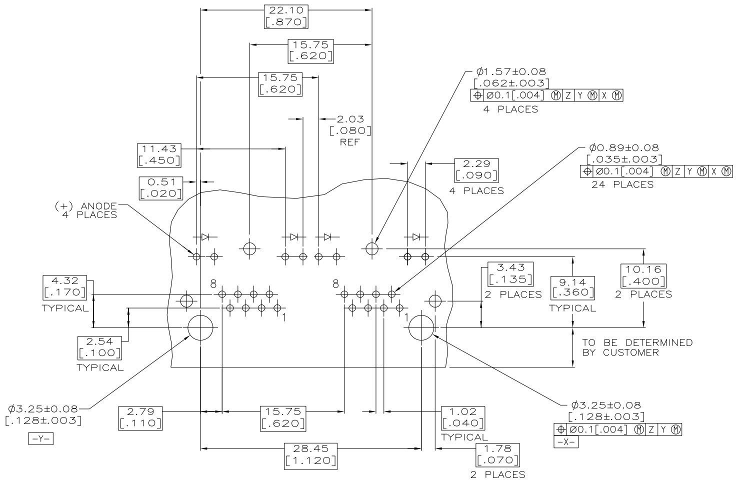
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3 SUGGESTED PANEL OPENING DIMENSIONS.

4 SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

5 SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.

6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT

(COMPONENT SIDE)

YELLOW	GREEN	6368419-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± 0.25[.01]
3 PLC ± 0.13[.005]
4 PLC ± –
ANGLES ± –

MATERIAL 1
FINISH 1

DWN 16JUN2005 L. VARELA – DOCK5
CHK 16JUN2005 J. WESTMAN
APVD 16JUN2005 S. FLICKINGER
PRODUCT SPEC 108–1163–4
APPLICATION SPEC 114–2154
WEIGHT –

tyco Electronics
Tyco Electronics Corporation
Harrisburg, Pa 17105–3608

NAME
INVERTED MODULAR JACK ASSEMBLY,
1X2, SHIELDED,
PANEL GROUND, WITH LEDS

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C-6368419	–

CUSTOMER DRAWING
SCALE 1:1
SHEET 1 OF 1
REV A